

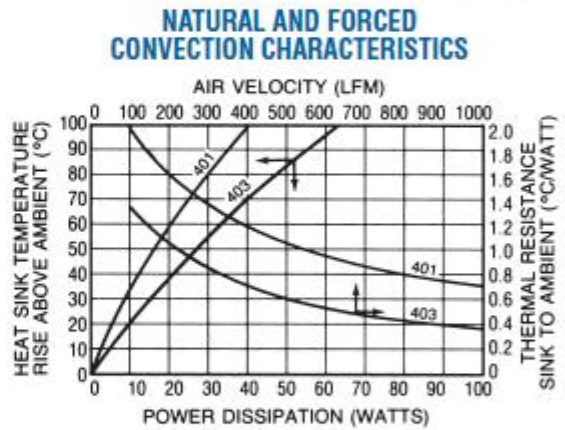
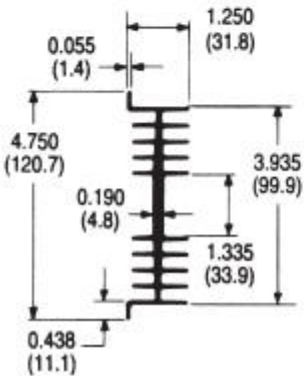
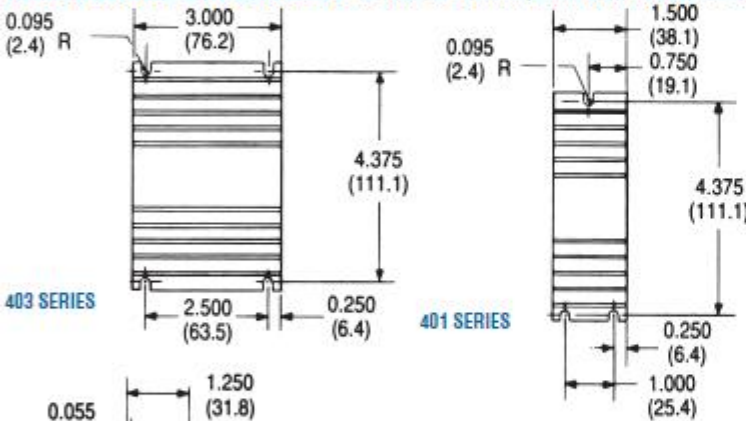
# 401/403 Series

Extruded Heat Sinks for Power Semiconductors



Standard P/N	Width in. (mm)	Overall Dimensions in. (mm)	Height in. (mm)	Semiconductor Mounting Hole Pattern	Thermal Performance at Typical Load		Weight lbs. (grams)
					Natural Convection	Forced Convection	
401A	4.750 (120.7)	1.500 (38.1)	1.250 (31.8)	(1) TO-3	80°C @ 30W	1.5° C/W @ 250 LFM	0.1500 (68.04)
401F	4.750 (120.7)	1.500 (38.1)	1.250 (31.8)	0.270 in. (6.9)-Dia Hole	80°C @ 30W	1.5° C/W @ 250 LFM	0.1500 (68.04)
401K	4.750 (120.7)	1.500 (38.1)	1.250 (31.8)	None	80°C @ 30W	1.5° C/W @ 250 LFM	0.1500 (68.04)
403A	4.750 (120.7)	3.000 (76.2)	1.250 (31.8)	(1) TO-3	55°C @ 30W	0.9° C/W @ 250 LFM	0.3500 (158.76)
403F	4.750 (120.7)	3.000 (76.2)	1.250 (31.8)	0.270 in. (6.9)-Dia Hole	55°C @ 30W	0.9° C/W @ 250 LFM	0.3500 (158.76)
403K	4.750 (120.7)	3.000 (76.2)	1.250 (31.8)	None	55°C @ 30W	0.9° C/W @ 250 LFM	0.3500 (158.76)

## MECHANICAL DIMENSIONS 401 AND 403 SERIES (EXTRUSION PROFILE 1024)



## SEMICONDUCTOR MOUNTING HOLES

